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NBSG11

2.5V/3.3V SiGe 1:2 Differential Clock Driver with RSECL* Outputs

*Reduced Swing ECL

Description

The NBSG11 is a 1-to-2 differential fanout buffer, optimized for low skew and Ultra-Low JITTER.

Inputs incorporate internal 50 Ω termination resistors and accept NECL (Negative ECL), PECL (Positive ECL), CML, LVCMOS, LVTTTL, or LVDS. Outputs are RSECL (Reduced Swing ECL), 400 mV.

Features

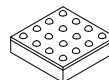
- Maximum Input Clock Frequency up to 12 GHz Typical
- Maximum Input Data Rate up to 12 Gb/s Typical
- 30 ps Typical Rise and Fall Times
- 125 ps Typical Propagation Delay
- RSPECL Output with Operating Range: $V_{CC} = 2.375\text{ V}$ to 3.465 V with $V_{EE} = 0\text{ V}$
- RSNECL Output with RSNECL or NECL Inputs with Operating Range: $V_{CC} = 0\text{ V}$ with $V_{EE} = -2.375\text{ V}$ to -3.465 V
- RSECL Output Level (400 mV Peak-to-Peak Output), Differential Output Only
- 50 Ω Internal Input Termination Resistors
- Compatible with Existing 2.5 V/3.3 V LVEP, EP, and LVEL Devices
- Pb-Free Packages are Available



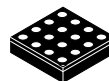
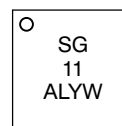
ON Semiconductor®

<http://onsemi.com>

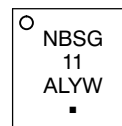
MARKING DIAGRAMS*



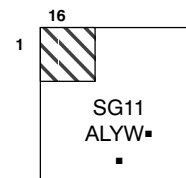
FCBGA-16
BA SUFFIX
CASE 489



FCLGA-16
MA SUFFIX
CASE 526



QFN-16
MN SUFFIX
CASE 485G



- A = Assembly Location
- L = Wafer Lot
- Y = Year
- W = Work Week
- = Pb-Free Package

(Note: Microdot may be in either location)

*For additional marking information, refer to Application Note AND8002/D.

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

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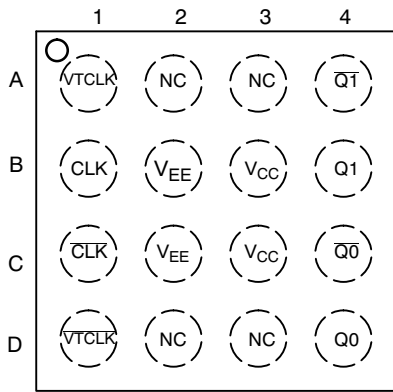


Figure 1. BGA-16 and LGA-16 Pinout (Top View)

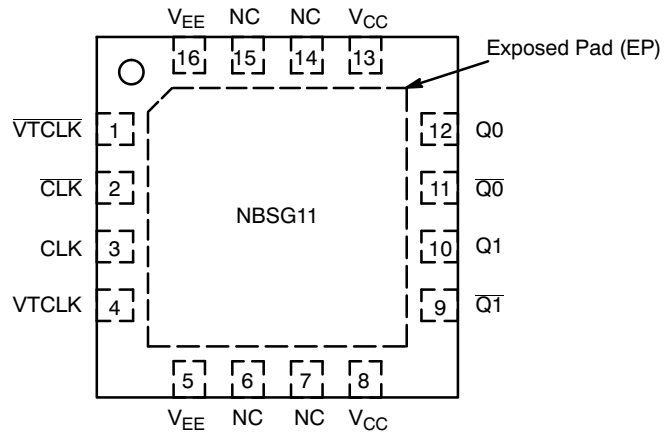


Figure 2. QFN-16 Pinout (Top View)

Table 1. PIN DESCRIPTION

| Pin | | Name | I/O | Description |
|-------------|-----------|----------|--------------------------------------|--|
| BGA | QFN | | | |
| D1 | 1 | VTCLK | - | Internal 50 Ω Termination Pin. See Table 2. |
| C1 | 2 | CLK | ECL, CML, LVCMOS, LVDS, LVTTTL Input | Inverted Differential Input. Internal 75 k Ω to V_{EE} and 36.5 k Ω to V_{CC} . |
| B1 | 3 | CLK | ECL, CML, LVCMOS, LVDS, LVTTTL Input | Noninverted Differential Input. Internal 75 k Ω to V_{EE} . |
| A1 | 4 | VTCLK | - | Internal 50 Ω Termination Pin. See Table 2. |
| B2,C2 | 5,16 | V_{EE} | - | Negative Supply Voltage |
| A2,A3,D2,D3 | 6,7,14,15 | NC | - | No Connect |
| B3,C3 | 8,13 | V_{CC} | - | Positive Supply Voltage |
| A4 | 9 | Q1 | RSECL Output | Inverted Differential Output 1. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2.0$ V. |
| B4 | 10 | Q1 | RSECL Output | Noninverted Differential Output 1. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2.0$ V. |
| C4 | 11 | Q0 | RSECL Output | Inverted Differential output 0. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2.0$ V. |
| D4 | 12 | Q0 | RSECL Output | Noninverted Differential Output 0. Typically Terminated with 50 Ω to $V_{TT} = V_{CC} - 2$ V. |
| N/A | - | EP | - | Exposed Pad (Note 2) |

1. The NC pins are electrically connected to the die and must be left open.
2. All V_{CC} and V_{EE} pins must be externally connected to Power Supply to guarantee proper operation. The thermally exposed pad on package bottom (see case drawing) must be attached to a heat-sinking conduit.
3. In the differential configuration when the input termination pins (VTCLK, VTCLK) are connected to a common termination voltage, and if no signal is applied then the device will be susceptible to self-oscillation.

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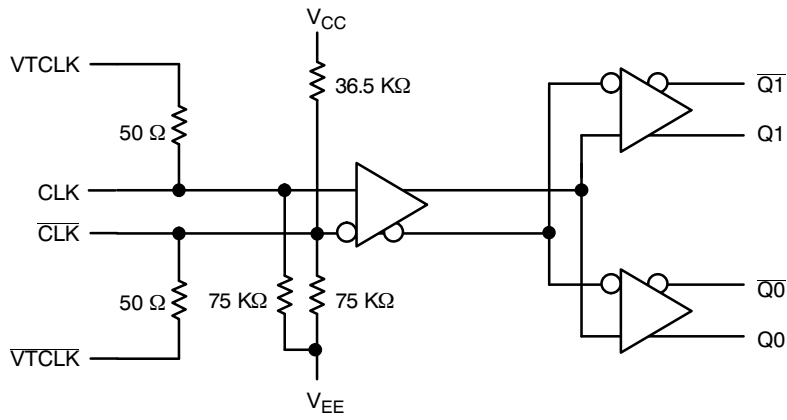


Figure 3. Logic Diagram

Table 2. INTERFACING OPTIONS

| INTERFACING OPTIONS | CONNECTIONS |
|---------------------|---|
| CML | Connect VTCLK and VTCLK-bar to V _{CC} |
| LVDS | Connect VTCLK and VTCLK-bar together |
| AC-COUPLED | Bias VTCLK and VTCLK-bar Inputs within (VIHCMR) Common Mode Range |
| RSECL, PECL, NECL | Standard ECL Termination Techniques |
| LVTTTL, LVCMOS | An external voltage should be applied to the unused complementary differential input. Nominal voltage is 1.5 V for LVTTTL and V _{CC} /2 for LVCMOS inputs. |

Table 3. ATTRIBUTES

| Characteristics | Value | |
|--|------------------------|----------------------|
| Internal Input Pulldown Resistor (CLK, CLK-bar) | 75 kΩ | |
| Internal Input Pullup Resistor (VTCLK) | 36.5 kΩ | |
| ESD Protection | Human Body Model | > 2 kV |
| | Machine Model | > 100 V |
| Moisture Sensitivity (Note 4) | Pb Pkg | Pb-Free Pkg |
| | FCLGA-16, FCBGA-16 | Level 3 |
| | QFN-16 | Level 1 |
| Flammability Rating | Oxygen Index: 28 to 34 | UL 94 V-0 @ 0.125 in |
| Transistor Count | 125 | |
| Meets or exceeds JEDEC Spec EIA/JESD78 IC Latchup Test | | |

4. For additional information, see Application Note AND8003/D.

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Table 4. MAXIMUM RATINGS

| Symbol | Parameter | Condition 1 | Condition 2 | Rating | Unit |
|---------------|--|---|--|----------------------------|------------------------------|
| V_{CC} | Positive Power Supply | $V_{EE} = 0\text{ V}$ | | 3.6 | V |
| V_{EE} | Negative Power Supply | $V_{CC} = 0\text{ V}$ | | -3.6 | V |
| V_I | Positive Input Negative Input | $V_{EE} = 0\text{ V}$ $V_{CC} = 0\text{ V}$ | $V_I \leq V_{CC}$ $V_I \geq V_{EE}$ | 3.6 -3.6 | V V |
| V_{INPP} | Differential Input Voltage $ D - \bar{D} $ | $V_{CC} - V_{EE} \geq 2.8\text{ V}$ $V_{CC} - V_{EE} < 2.8\text{ V}$ | | 2.8 $ V_{CC} - V_{EE} $ | V V |
| I_{out} | Output Current | Continuous Surge | | 25 50 | mA mA |
| T_A | Operating Temperature Range | 16 FCBGA, FCLGA 16 QFN | | -40 to +70 -40 to +85 | °C |
| T_{stg} | Storage Temperature Range | | | -65 to +150 | °C |
| θ_{JA} | Thermal Resistance (Junction-to-Ambient) (Note 5) | 0 lfpm 500 lfpm 0 lfpm 500 lfpm | 16 FCBGA, FCLGA 16 FCBGA, FCLGA 16 QFN 16 QFN | 108 86 41.6 35.2 | °C/W °C/W °C/W °C/W |
| θ_{JC} | Thermal Resistance (Junction-to-Case) | 1S2P (Note 5) 2S2P (Note 6) | 16 FCBGA, FCLGA 16 QFN | 5.0 4.0 | °C/W °C/W |
| T_{sol} | Wave Solder Pb Pb-Free | | | 225 265 | °C |

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

5. JEDEC standard multilayer board – 1S2P (1 signal, 2 power).

6. JEDEC standard multilayer board – 2S2P (2 signal, 2 power) with 8 filled thermal vias under exposed pad.

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Table 5. DC CHARACTERISTICS, INPUT WITH RSPECL OUTPUT $V_{CC} = 2.5\text{ V}$; $V_{EE} = 0\text{ V}$ (Note 7)

| Symbol | Characteristic | -40°C | | | 25°C | | | 70°C(LGA)/85°C(QFN)** | | | Unit |
|-------------|--|---------------------------|-----------------------------|--------------------------|---------------------------|-----------------------------|--------------------------|---------------------------|-----------------------------|--------------------------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Negative Power Supply Current | 45 | 60 | 75 | 45 | 60 | 75 | 45 | 60 | 75 | mA |
| V_{OH} | Output HIGH Voltage (Note 8) | 1450 | 1530 | 1575 | 1525 | 1565 | 1600 | 1550 | 1590 | 1625 | mV |
| V_{OUTPP} | Output Amplitude Voltage | 350 | 410 | 525 | 350 | 410 | 525 | 350 | 410 | 525 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) (Note 10) | $V_{CC} - 1435\text{ mV}$ | $V_{CC} - 1000\text{ mV}^*$ | V_{CC} | $V_{CC} - 1435\text{ mV}$ | $V_{CC} - 1000\text{ mV}^*$ | V_{CC} | $V_{CC} - 1435\text{ mV}$ | $V_{CC} - 1000\text{ mV}^*$ | V_{CC} | V |
| V_{IL} | Input LOW Voltage (Single-Ended) (Note 11) | $V_{IH} - 2.5\text{ V}$ | $V_{CC} - 1400\text{ mV}^*$ | $V_{IH} - 150\text{ mV}$ | $V_{IH} - 2.5\text{ V}$ | $V_{CC} - 1400\text{ mV}^*$ | $V_{IH} - 150\text{ mV}$ | $V_{IH} - 2.5\text{ V}$ | $V_{CC} - 1400\text{ mV}^*$ | $V_{IH} - 150\text{ mV}$ | V |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 9) | 1.2 | | 2.5 | 1.2 | | 2.5 | 1.2 | | 2.5 | V |
| R_{TIN} | Internal Input Termination Resistor | 45 | 50 | 55 | 45 | 50 | 55 | 45 | 50 | 55 | Ω |
| I_{IH} | Input HIGH Current (@ V_{IH} , V_{IHMAX}) | | 80 | 150 | | 80 | 150 | | 80 | 150 | μA |
| I_{IL} | Input LOW Current (@ V_{IL} , V_{ILMIN}) | | 25 | 100 | | 25 | 100 | | 25 | 100 | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

*Typicals used for testing purposes.

**The device packaged in FCLGA-16 have maximum temperature specification of 70°C and devices packaged in QFN-16 have maximum temperature specification of 85°C.

7. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.125 V to -0.965 V.

8. All loading with 50 Ω to $V_{CC} - 2.0\text{ V}$. V_{OH}/V_{OL} measured at V_{IH}/V_{IL} .

9. V_{IHCMR} min varies 1:1 with V_{EE} . V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

10. V_{IH} cannot exceed V_{CC} .

11. V_{IL} always $\geq V_{EE}$.

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Table 6. DC CHARACTERISTICS, INPUT WITH RSPECL OUTPUT $V_{CC} = 3.3\text{ V}$; $V_{EE} = 0\text{ V}$ (Note 12)

| Symbol | Characteristic | -40°C | | | 25°C | | | 70°C(LGA)/85°C(QFN)** | | | Unit |
|-------------|--|---------------------------|-----------------------------|--------------------------|---------------------------|-----------------------------|--------------------------|---------------------------|-----------------------------|--------------------------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Negative Power Supply Current | 45 | 60 | 75 | 45 | 60 | 75 | 45 | 60 | 75 | mA |
| V_{OH} | Output HIGH Voltage (Note 13) | 2250 | 2330 | 2375 | 2325 | 2365 | 2400 | 2350 | 2390 | 2425 | mV |
| V_{OUTPP} | Output Amplitude Voltage | 350 | 410 | 525 | 350 | 410 | 525 | 350 | 410 | 525 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) (Note 15) | $V_{CC} - 1435\text{ mV}$ | $V_{CC} - 1000\text{ mV}^*$ | V_{CC} | $V_{CC} - 1435\text{ mV}$ | $V_{CC} - 1000\text{ mV}^*$ | V_{CC} | $V_{CC} - 1435\text{ mV}$ | $V_{CC} - 1000\text{ mV}^*$ | V_{CC} | V |
| V_{IL} | Input LOW Voltage (Single-Ended) (Note 16) | $V_{IH} - 2.5\text{ V}$ | $V_{CC} - 1400\text{ mV}^*$ | $V_{IH} - 150\text{ mV}$ | $V_{IH} - 2.5\text{ V}$ | $V_{CC} - 1400\text{ mV}^*$ | $V_{IH} - 150\text{ mV}$ | $V_{IH} - 2.5\text{ V}$ | $V_{CC} - 1400\text{ mV}^*$ | $V_{IH} - 150\text{ mV}$ | V |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Note 14) (Differential Configuration) | 1.2 | | 3.3 | 1.2 | | 3.3 | 1.2 | | 3.3 | V |
| R_{TIN} | Internal Input Termination Resistor | 45 | 50 | 55 | 45 | 50 | 55 | 45 | 50 | 55 | Ω |
| I_{IH} | Input HIGH Current (@ V_{IH} , V_{IHMAX}) | | 80 | 150 | | 80 | 150 | | 80 | 150 | μA |
| I_{IL} | Input LOW Current (@ V_{IL} , V_{ILMIN}) | | 25 | 100 | | 25 | 100 | | 25 | 100 | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

12. Input and output parameters vary 1:1 with V_{CC} . V_{EE} can vary +0.925 V to -0.165 V.

13. All loading with 50 Ω to $V_{CC} - 2.0\text{ V}$. V_{OH}/V_{OL} measured at V_{IH}/V_{IL} .

14. V_{IHCMR} min varies 1:1 with V_{EE} . V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

15. V_{IH} cannot exceed V_{CC} .

16. V_{IL} always $\geq V_{EE}$.

*Typicals used for testing purposes.

**The device packaged in FCLGA-16 have maximum temperature specification of 70°C and devices packaged in QFN-16 have maximum temperature specification of 85°C.

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Table 7. DC CHARACTERISTICS, NECL OR RSNECL INPUT WITH NECL OUTPUT

$V_{CC} = 0\text{ V}$; $V_{EE} = -3.465\text{ V}$ to -2.375 V (Note 17)

| Symbol | Characteristic | -40°C | | | 25°C | | | 70°C(LGA)/85°C(QFN)** | | | Unit |
|-------------|---|-------------------------|---------------------------|------------------------|-------------------------|---------------------------|------------------------|-------------------------|---------------------------|------------------------|---------------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| I_{EE} | Negative Power Supply Current | 45 | 60 | 75 | 45 | 60 | 75 | 45 | 60 | 75 | mA |
| V_{OH} | Output HIGH Voltage (Note 18) | -1050 | -970 | -925 | -975 | -935 | -900 | -950 | -910 | -875 | mV |
| V_{OUTPP} | Output Amplitude Voltage | 350 | 410 | 525 | 350 | 410 | 525 | 350 | 410 | 525 | mV |
| V_{IH} | Input HIGH Voltage (Single-Ended) (Note 20) | $V_{CC}-1435\text{ mV}$ | $V_{CC}-1000\text{ mV}^*$ | V_{CC} | $V_{CC}-1435\text{ mV}$ | $V_{CC}-1000\text{ mV}^*$ | V_{CC} | $V_{CC}-1435\text{ mV}$ | $V_{CC}-1000\text{ mV}^*$ | V_{CC} | V |
| V_{IL} | Input LOW Voltage (Single-Ended) (Note 21) | $V_{IH}-2.5\text{ V}$ | $V_{CC}-1400\text{ mV}^*$ | $V_{IH}-150\text{ mV}$ | $V_{IH}-2.5\text{ V}$ | $V_{CC}-1400\text{ mV}^*$ | $V_{IH}-150\text{ mV}$ | $V_{IH}-2.5\text{ V}$ | $V_{CC}-1400\text{ mV}^*$ | $V_{IH}-150\text{ mV}$ | V |
| V_{IHCMR} | Input HIGH Voltage Common Mode Range (Differential Configuration) (Note 19) | $V_{EE}+1.2$ | | 0.0 | $V_{EE}+1.2$ | | 0.0 | $V_{EE}+1.2$ | | 0.0 | V |
| R_{TIN} | Internal Input Termination Resistor | 45 | 50 | 55 | 45 | 50 | 55 | 45 | 50 | 55 | Ω |
| I_{IH} | Input HIGH Current (@ V_{IH} , V_{IHMAX}) | | 80 | 150 | | 80 | 150 | | 80 | 150 | μA |
| I_{IL} | Input LOW Current (@ V_{IL} , V_{ILMIN}) | | 25 | 100 | | 25 | 100 | | 25 | 100 | μA |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lpm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

17. Input and output parameters vary 1:1 with V_{CC} .

18. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$. V_{OH}/V_{OL} measured at V_{IH}/V_{IL} .

19. V_{IHCMR} min varies 1:1 with V_{EE} . V_{IHCMR} max varies 1:1 with V_{CC} . The V_{IHCMR} range is referenced to the most positive side of the differential input signal.

20. V_{IH} cannot exceed V_{CC} .

21. V_{IL} always $\geq V_{EE}$.

*Typicals used for testing purposes.

**The device packaged in FCLGA-16 have maximum temperature specification of 70°C and devices packaged in QFN-16 have maximum temperature specification of 85°C.

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Table 8. AC CHARACTERISTICS for FCLGA-16

$V_{CC} = 0\text{ V}$; $V_{EE} = -3.465\text{ V}$ to -2.375 V or $V_{CC} = 2.375\text{ V}$ to 3.465 V ; $V_{EE} = 0\text{ V}$

| Symbol | Characteristic | -40°C | | | 25°C | | | 70°C | | | Unit |
|--------------------------|--|--------|--------------|----------------|--------|--------------|----------------|--------|--------------|----------------|------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| f_{max} | Maximum Frequency (See Figure 4. $F_{max}/JITTER$) (Note 22) | 10.709 | 12 | | 10.709 | 12 | | 10.709 | 12 | | GHz |
| t_{PLH} , t_{PHL} | Propagation Delay to Output Differential | 90 | 125 | 160 | 90 | 125 | 160 | 90 | 125 | 160 | ps |
| t_{SKEW} | Duty Cycle Skew (Note 23) Within-Device Skew (Note 24) Device-to-Device Skew (Note 25) | | 3 6 25 | 15 15 50 | | 3 6 25 | 15 15 50 | | 3 6 25 | 15 15 50 | ps |
| t_{JITTER} | RMS Random Clock Jitter $f_{in} < 10\text{ GHz}$ Peak-to-Peak Data Dependent Jitter $f_{in} < 10\text{ Gb/s}$ | | 0.2 TBD | 1 | | 0.2 TBD | 1 | | 0.2 TBD | 1 | ps |
| V_{INPP} | Input Voltage Swing/Sensitivity (Differential Configuration) (Note 26) | 75 | | 2600 | 75 | | 2600 | 75 | | 2600 | mV |
| t_r t_f | Output Rise/Fall Times (20% - 80%) @ 1 GHz | 20 | 30 | 55 | 20 | 30 | 55 | 20 | 30 | 55 | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

22. Measured using a 500 mV source, 50% duty cycle clock source. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$. For minimum f_{max} value of 10.709 GHz, output amplitude is approximately 200 mV (as shown in Figure 4, where output P-P spec is shown as a minimum/guarantee of around 150 mV). Input edge rates 40 ps (20% - 80%).

23. See Figure 5. $t_{SKEW} = |t_{PLH} - t_{PHL}|$ for a nominal 50% Differential Clock Input Waveform.

24. Within-Device skew is defined as identical transitions on similar paths through a device.

25. Device-to-device skew for identical transitions at identical V_{CC} levels.

26. V_{INPP} (MAX) cannot exceed $V_{CC} - V_{EE}$.

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Table 9. AC CHARACTERISTICS for QFN-16 $V_{CC} = 0\text{ V}$; $V_{EE} = -3.465\text{ V to } -2.375\text{ V}$ or $V_{CC} = 2.375\text{ V to } 3.465\text{ V}$; $V_{EE} = 0\text{ V}$

| Symbol | Characteristic | -40°C | | | 25°C | | | 85°C | | | Unit |
|--------------------------|--|-------|--------------|----------------|------|--------------|----------------|------|--------------|----------------|------|
| | | Min | Typ | Max | Min | Typ | Max | Min | Typ | Max | |
| f_{max} | Maximum Frequency (See Figure 4. $F_{max}/JITTER$) (Note 27) | 10.5 | 12 | | 10.5 | 12 | | 10.5 | 12 | | GHz |
| t_{PLH} , t_{PHL} | Propagation Delay to Output Differential | 90 | 125 | 160 | 90 | 125 | 160 | 90 | 125 | 160 | ps |
| t_{SKEW} | Duty Cycle Skew (Note 28) Within-Device Skew (Note 29) Device-to-Device Skew (Note 30) | | 3 6 25 | 15 15 50 | | 3 6 25 | 15 15 50 | | 3 6 25 | 15 15 50 | ps |
| t_{JITTER} | RMS Random Clock Jitter $f_{in} < 10\text{ GHz}$ Peak-to-Peak Data Dependent Jitter $f_{in} < 10\text{ Gb/s}$ | | 0.2 TBD | 1 | | 0.2 TBD | 1 | | 0.2 TBD | 1 | ps |
| V_{INPP} | Input Voltage Swing/Sensitivity (Differential Configuration) (Note 31) | 75 | | 2600 | 75 | | 2600 | 75 | | 2600 | mV |
| t_r t_f | Output Rise/Fall Times (20% - 80%) @ 1 GHz | 15 | 30 | 55 | 20 | 30 | 55 | 20 | 30 | 55 | ps |

NOTE: Device will meet the specifications after thermal equilibrium has been established when mounted in a test socket or printed circuit board with maintained transverse airflow greater than 500 lfm. Electrical parameters are guaranteed only over the declared operating temperature range. Functional operation of the device exceeding these conditions is not implied. Device specification limit values are applied individually under normal operating conditions and not valid simultaneously.

27. Measured using a 500 mV source, 50% duty cycle clock source. All loading with $50\ \Omega$ to $V_{CC} - 2.0\text{ V}$. For minimum f_{max} value of 10.5 GHz, output amplitude is approximately 200 mV (as shown in Figure 4, where output P-P spec is shown as a minimum/guarantee of around 150 mV). Input edge rates 40 ps (20% - 80%).

28. See Figure 5. $t_{SKEW} = |t_{PLH} - t_{PHL}|$ for a nominal 50% Differential Clock Input Waveform.

29. Within-Device skew is defined as identical transitions on similar paths through a device.

30. Device-to-device skew for identical transitions at identical V_{CC} levels.

31. V_{INPP} (MAX) cannot exceed $V_{CC} - V_{EE}$.

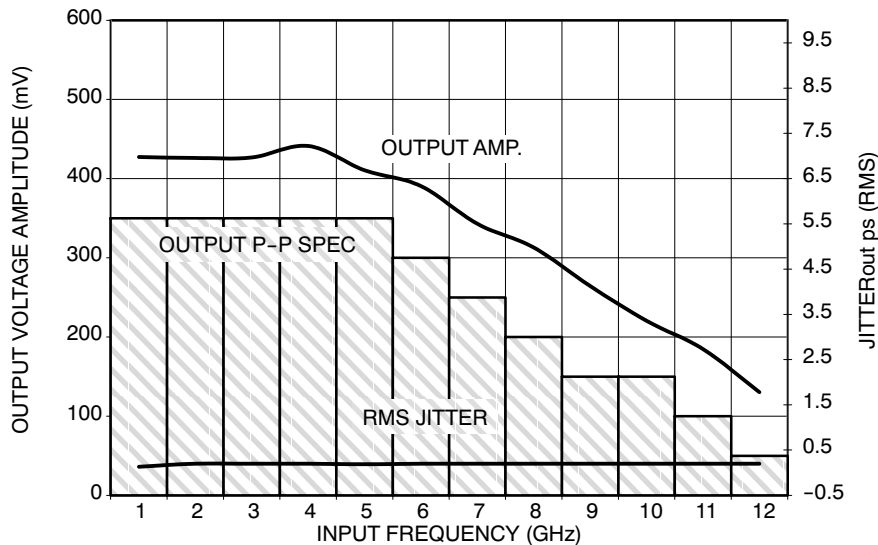


Figure 4. Output Voltage Amplitude (V_{OUTPP}) / RMS Jitter vs. Input Frequency (f_{in}) at Ambient Temperature (Typical)

NBSG11

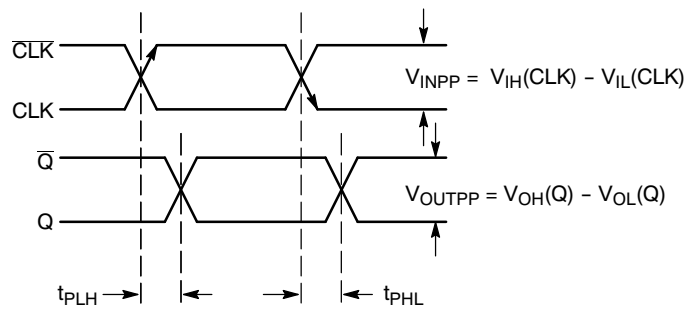


Figure 5. AC Reference Measurement

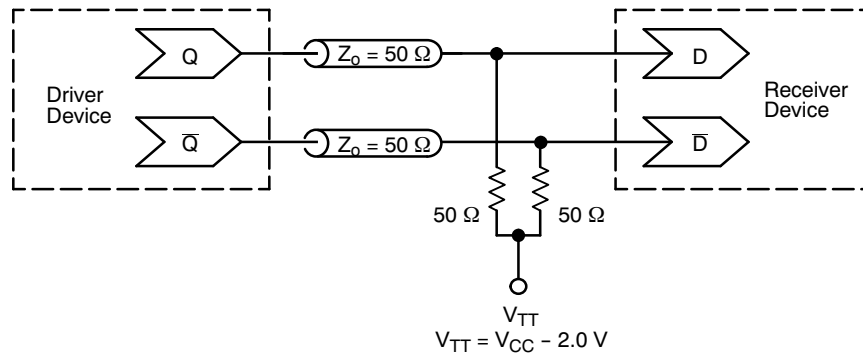


Figure 6. Typical Termination for Output Driver and Device Evaluation
(See Application Note AND8020/D – Termination of ECL Logic Devices.)

ORDERING INFORMATION

| Device | Package | Shipping [†] |
|--------------|-------------------------------|---|
| NBSG11BA | FCBGA-16 | 100 Units / Tray (Contact Sales Representative) |
| NBSG11BAR2 | FCBGA-16 | 100 / Tape & Reel (Contact Sales Representative) |
| NBSG11MAG | FCLGA-16, 4x4 mm (Pb-Free) | 100 Units / Tray (Contact Sales Representative) |
| NBSG11MAHTBG | FCLGA-16, 4x4 mm (Pb-Free) | 100 / Tape & Reel |
| NBSG11MN | QFN-16 | 123 Units / Rail |
| NBSG11MNG | QFN-16 (Pb-Free) | 123 Units / Rail |
| NBSG11MNR2 | QFN-16 | 3000 / Tape & Reel |
| NBSG11MNR2G | QFN-16 (Pb-Free) | 3000 / Tape & Reel |

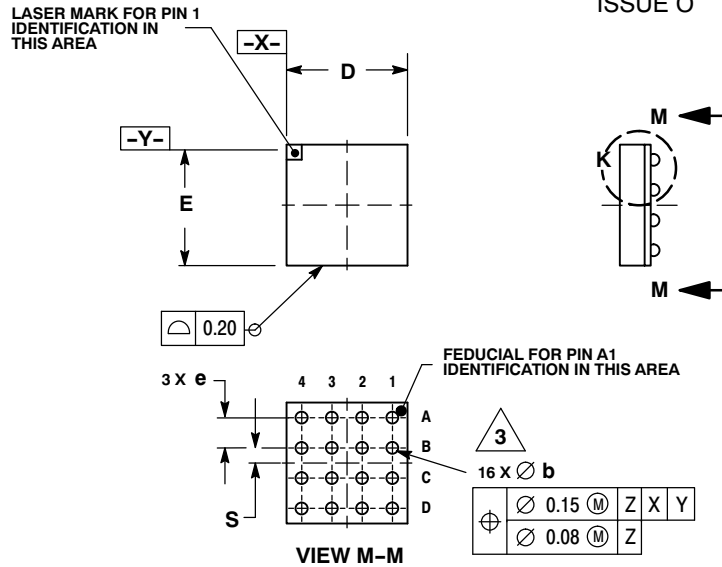
| Board | Description |
|-------------|---------------------------|
| NBSG11BAEVB | NBSG11BA Evaluation Board |

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

NBSG11

PACKAGE DIMENSIONS

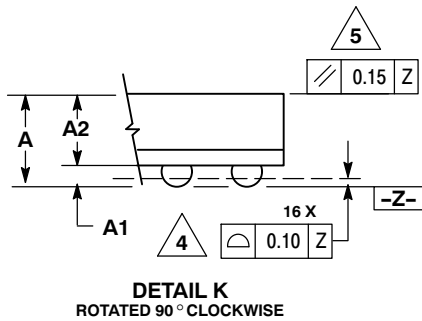
FCBGA-16
BA SUFFIX
 PLASTIC 4X4 (mm) BGA FLIP CHIP PACKAGE
 CASE 489-01
 ISSUE O



NOTES:

1. DIMENSIONS ARE IN MILLIMETERS.
2. INTERPRET DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 1994.
3. DIMENSION b IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO DATUM PLANE Z.
4. DATUM Z (SEATING PLANE) IS DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
5. PARALLELISM MEASUREMENT SHALL EXCLUDE ANY EFFECT OF MARK ON TOP SURFACE OF PACKAGE.

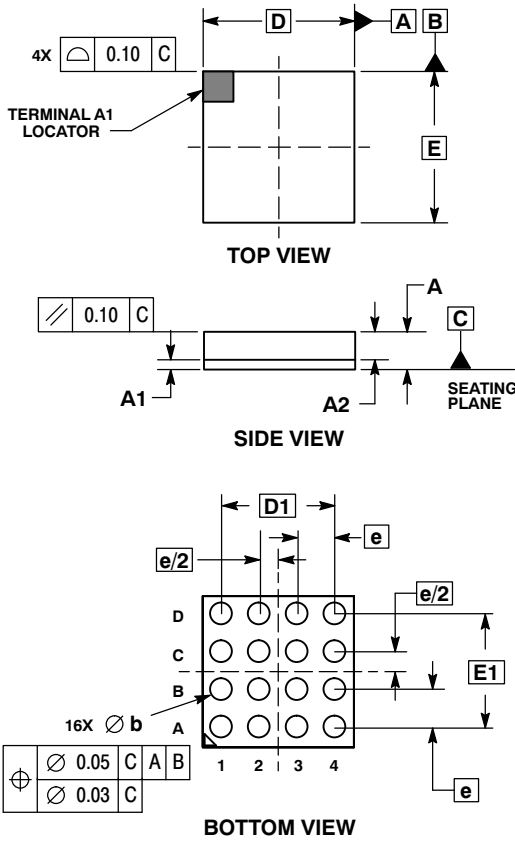
| MILLIMETERS | | |
|-------------|------|------|
| DIM | MIN | MAX |
| A | 1.40 | MAX |
| A1 | 0.25 | 0.35 |
| A2 | 1.20 | REF |
| b | 0.30 | 0.50 |
| D | 4.00 | BSC |
| E | 4.00 | BSC |
| e | 1.00 | BSC |
| S | 0.50 | BSC |



NBSG11

PACKAGE DIMENSIONS

16 PIN LGA 4x4, 1.0P
CASE 526AB-01
ISSUE C

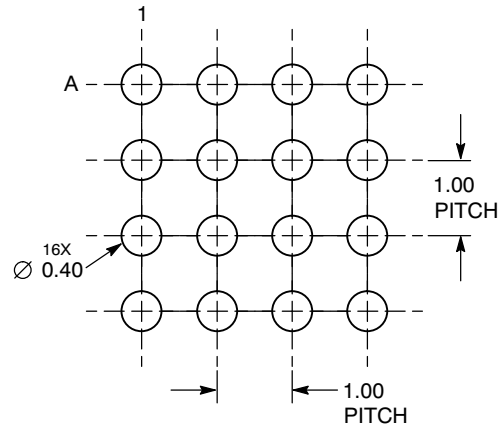


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.

| MILLIMETERS | | | |
|-------------|----------|------|------|
| DIM | MIN | TYP | MAX |
| A | 0.89 | 0.96 | 1.03 |
| A1 | 0.22 | 0.26 | 0.30 |
| A2 | 0.67 | 0.70 | 0.73 |
| b | 0.30 | 0.40 | 0.50 |
| D | 4.00 BSC | | |
| D1 | 3.00 BSC | | |
| E | 4.00 BSC | | |
| E1 | 3.00 BSC | | |
| e | 1.00 BSC | | |

SOLDERING FOOTPRINT*

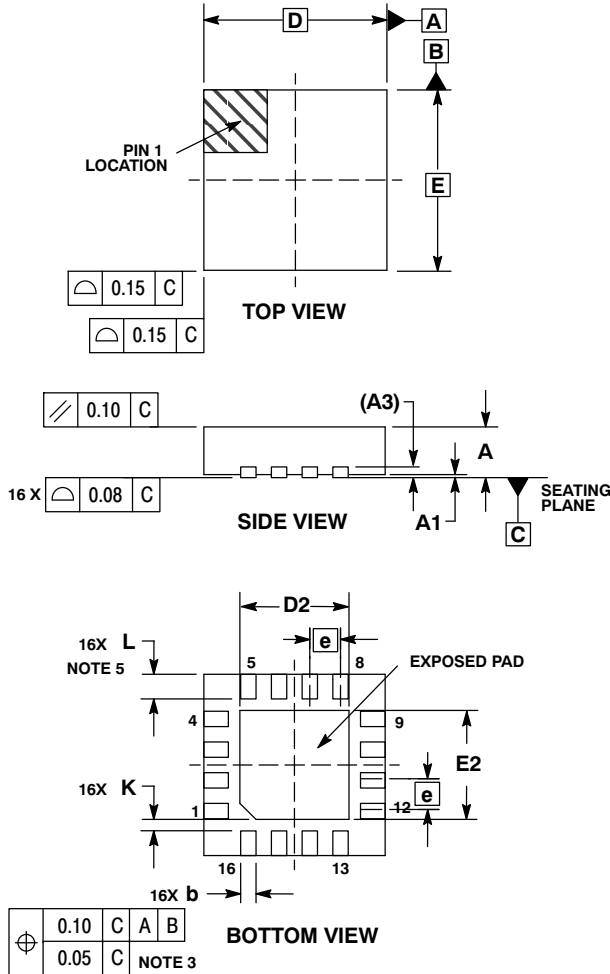


*For additional information on our Pb-Free strategy and soldering details, please download the ON Semiconductor Soldering and Mounting Techniques Reference Manual, SOLDERRM/D.

NBSG11

PACKAGE DIMENSIONS

16 PIN QFN
CASE 485G-01
ISSUE C

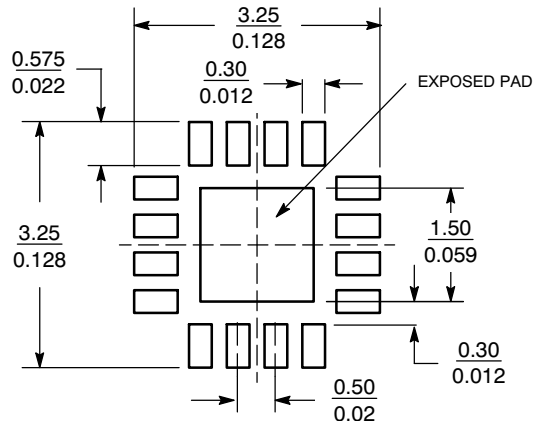


NOTES:

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS.
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.
5. L_{max} CONDITION CAN NOT VIOLATE 0.2 MM MINIMUM SPACING BETWEEN LEAD TIP AND FLAG

| DIM | MILLIMETERS | |
|-----|-------------|------|
| | MIN | MAX |
| A | 0.80 | 1.00 |
| A1 | 0.00 | 0.05 |
| A3 | 0.20 | REF |
| b | 0.18 | 0.30 |
| D | 3.00 | BSC |
| D2 | 1.65 | 1.85 |
| E | 3.00 | BSC |
| E2 | 1.65 | 1.85 |
| e | 0.50 | BSC |
| K | 0.18 | TYP |
| L | 0.30 | 0.50 |

SOLDERING FOOTPRINT*



SCALE 10:1 (mm/inches)

*For additional information on our Pb-Free strategy and solder details, please download the ON Semiconductor Soldering & Mounting Techniques Reference Manual, SOLDERRM/D.

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